



PolyZen Devices

Polymer Protected Zener Diode

PolyZen devices are polymer enhanced precision Zener diode micro-assemblies that help protect sensitive electronics from damage caused by inductive voltage spikes, voltage transients, incorrect power supplies and reverse bias.

The PolyZen micro-assembly incorporates a stable Zener diode for precise voltage clamping and a resistively non-linear, polymeric positive temperature coefficient (PPTC) layer that responds to either diode heating or overcurrent events by transitioning from a low to high resistance state.

PolyZen devices help provide resettable protection against damage caused by multi-watt fault events and require only 0.7W power dissipation. In the event of sustained high power conditions, the PPTC element of the device "trips" to limit current and generate voltage drop. This functionality helps protect both the Zener and the follow-on electronics, effectively increasing the diode's power handling capacity.



Benefits

- Helps shield downstream electronics from overvoltage and reverse bias
- Trip events shut out overvoltage and reverse bias sources
- Analog nature of trip events minimize upstream inductive spikes
- Helps reduce design costs with single component placement and minimal heat sinking requirements

Features

- Overvoltage transient suppression
- Hold currents up to 2.3A
- Time delayed, overvoltage trip
- Time delayed, reverse bias trip
- Power handling on the order of 30 watts
- Integrated device construction
- RoHS compliant

Applications

- Portable media players
- Global positioning systems
- Hard disk drive 5V & 12V bus

- · Automotive peripheral input power
- DC power port protection
- Industrial handheld POS

Figure PZ1 Typical Application Block Diagram for PolyZen Devices

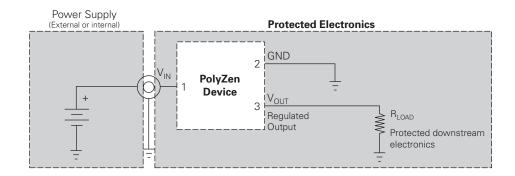


Table PZ1 Electrical Characteristics for PolyZen Devices

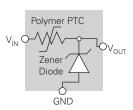
(Performance ratings @ 25°C unless otherwise specified)

		V _Z (V)						V _{INT MAX}		I _{FLT MAX}		
	Part Number	Min.	Тур.	Max.	I _{Zt} (A)	I _{HOLD} @ 20°C (A)	\mathbf{R}_{Typ} (Ω)	R _{1MAX} (Ω)	V _{INT MAX} (V)	Test Current (A)	I _{FLT MAX} (A)	Test Voltage (V)
	ZEN056V130A24LS	5.45	5.6	5.75	0.1	1.3	0.12	0.16	24V	3A	10/-40	+24/-16V
NEW	ZEN065V130A24LS	6.35	6.5	6.65	0.1	1.3	0.12	0.16	24V	3A	+6/-40	+24/-16V
	ZEN132V130A24LS	13.20	13.4	13.60	0.1	1.3	0.12	0.16	24V	3A	2/-40	+24/-16V
	ZEN164V130A24LS	16.10	16.4	16.60	0.1	1.3	0.12	0.16	24V	3A	1.25/-40	+24/-16V
	ZEN056V230A16LS	5.45	5.6	5.75	0.1	2.3	0.04	0.06	16V	5A	5/-40	+16/-12V
	ZEN065V230A16LS	6.35	6.5	6.65	0.1	2.3	0.04	0.06	16V	5A	3.5/-40	+16/-12V
Coming* Soon	ZEN132V230A16LS	13.20	13.4	13.60	0.1	2.3	0.04	0.06	16V	5A	TBD/-40	+16/-12V
Coming* Soon	ZEN056V075A48LS	5.45	5.6	5.75	0.1	0.75	0.28	0.45	48V	3A	+10/-40	+48/-16V
NEW	ZEN132V075A48LM	13.20	13.4	13.60	0.1	0.75	0.28	0.45	48V	ЗА	+2/-40	+48/-16V

^{*} Data is preliminary

Table PZ2 Definition of Terms for PolyZen Devices

V _Z	Zener clamping voltage measured at current I _{Zt} and 20°C.
I _{Zt}	Test current at which V _Z is measured.
I _{HOLD}	Maximum steady state current I_{PTC} that will not generate a trip event at the specified temperature. Ratings assume $I_{FLT} = 0A$.
R _{Typ}	Typical resistance between V_{IN} and V_{OUT} pins when the device is at room temperature.
R _{1MAX}	The maximum resistance between V_{IN} and V_{OUT} pins, at room temperature, one hour after first trip or after reflow soldering.
I _{FLT}	Current flowing through the Zener diode.
I _{FLT MAX}	Maximum RMS fault current the Zener diode component of the device can withstand and remain resettable; testing is conducted at rated voltage with no load connected to V_{OUT} .
V _{INT MAX}	The voltage ($V_{IN} - V_{OUT}$ "post trip") at which typical qualification devices (98% devices, 95% confidence) survived at least 100 trip cycles and 24 hours trip endurance when "tripped" at the specified voltage and current (I_{PTC}).
Trip Event	A condition where the PPTC transitions to a high resistance state, thereby limiting I_{PTC} , and significantly increasing the voltage drop between V_{IN} and V_{OUT} .



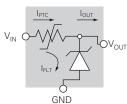
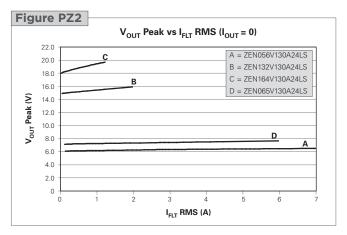
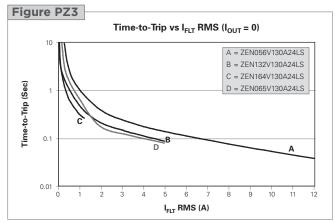
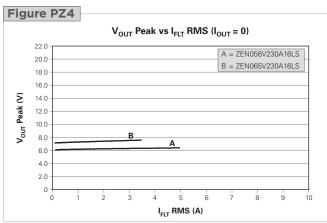
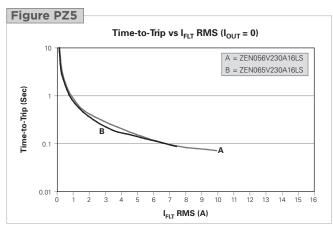


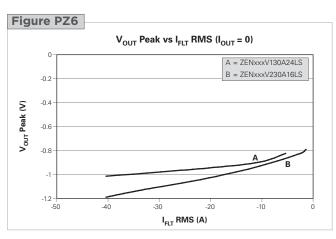
Figure PZ2-PZ15 Typical Performance Curves for PolyZen Devices

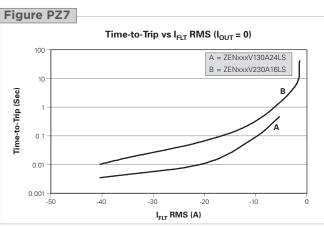


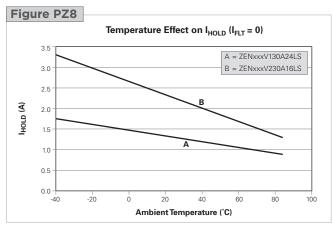


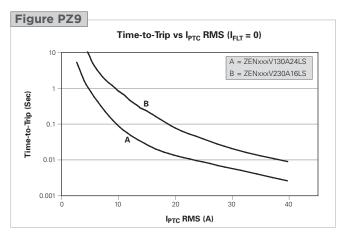


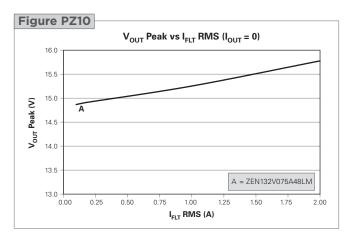


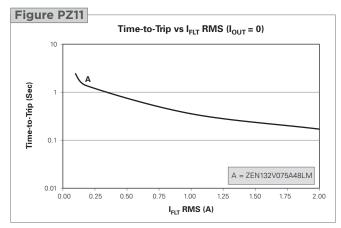


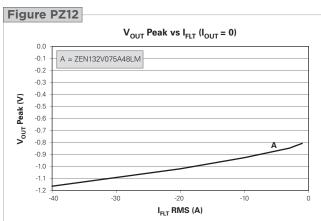


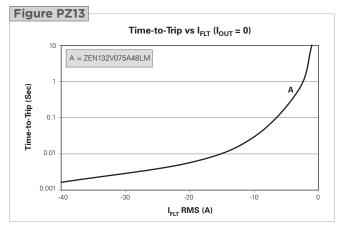


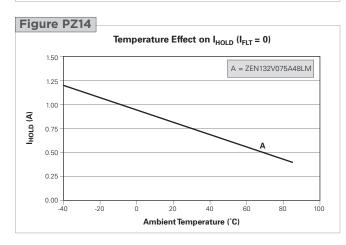












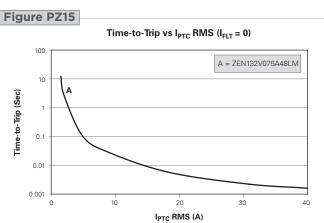
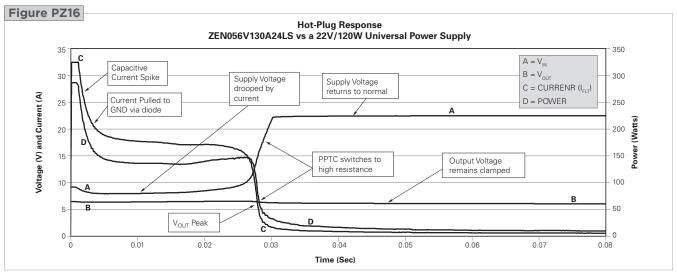
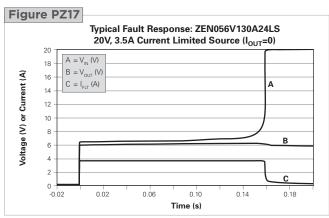
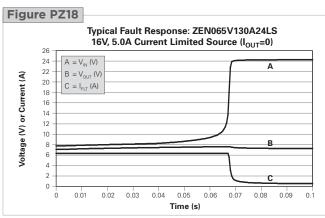


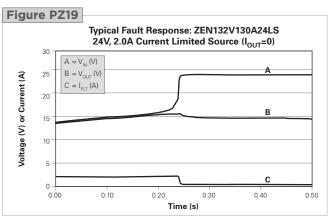
Table PZ3 General Characteristics for PolyZen Devices							
Operating temperature range	-40° to +85°C						
Storage temperature	-40° to +85°C						
ESD withstand	15kV	Human body model					
Diode capacitance	4200pF	Typical @ 1MHz, 1V RMS					
Construction	RoHS compliant						

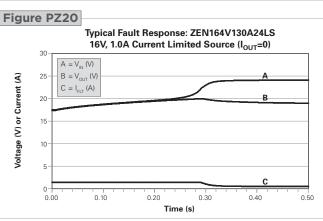
Figure PZ16-PZ23 Basic Operation Examples for PolyZen Devices

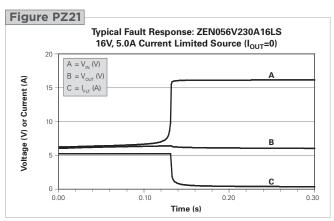


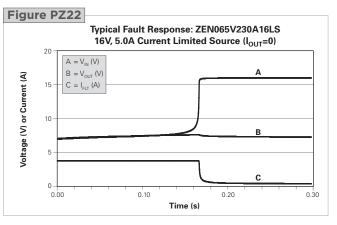




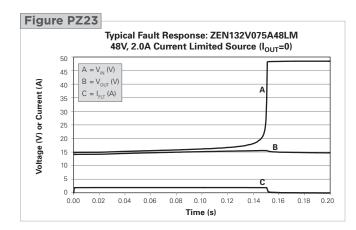












Packaging and Marking Information for PolyZen Devices

Part Number	Bag Quantity	Tape & Reel Quantity	Standard Package	
ZENxxxVyyyAzzLS	-	3,000	15,000	

Table PZ5 Dimensions for PolyZen Devices in Millimeters (Inches)

	Α			В	(С	
	Min.	Max.	Min.	Max.	Min.	Max.	
mm	3.85	4.15	3.85	4.15	1.4	2.0	
inch	(0.150)	(0.163)	(0.152)	(0.163)	(0.060)	(0.081)	

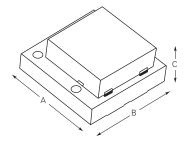
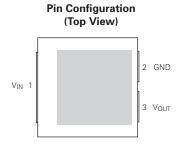
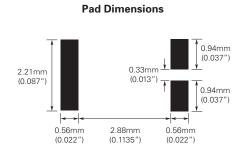


Table PZ6 Pad Layout and Configuration Information for PolyZen Devices

Pin Number	Pin Name	Pin Function			
1	V _{IN}	V _{IN} = Protected input to Zener diode			
2	GND	GND = Ground			
3	V _{OUT}	V _{OUT} = Zener regulated voltage output			



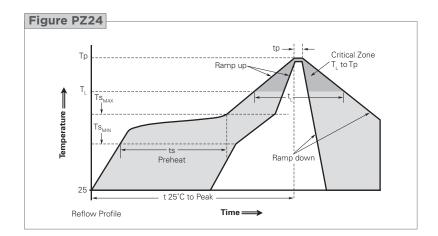




Solder Reflow and Rework Recommendation for PolyZen Devices

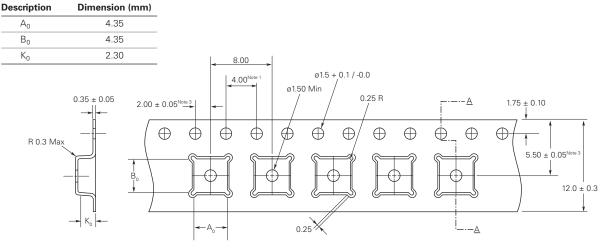
Classification Reflow Profiles					
Profile Feature	Pb-Free Assembly				
Average ramp up rate (Ts _{MAX} to Tp)	3°C/second max.				
Preheat					
• Temperature min. (Ts _{MIN})	150°C				
• Temperature max. (Ts _{MAX})	200°C				
• Time (ts _{MIN} to ts _{MAX})	60-180 seconds				
Time maintained above:					
• Temperature (T _L)	217°C				
• Time (t _L)	60-150 seconds				
Peak/Classification temperature (Tp)	260°C				
Time within 5°C of actual peak temperature					
Time (tp)	20-40 seconds				
Ramp down rate	6°C/second max.				
Time 25°C to peak temperature	8 minutes max.				

Note: All temperatures refer to topside of the package, measured on the package body surface.



Tape and Reel Specifications for PolyZen Devices (in Millimeters)

Figure PZ25 EIA Referenced Taped Component Dimensions for PolyZen Devices (in Millimeters)

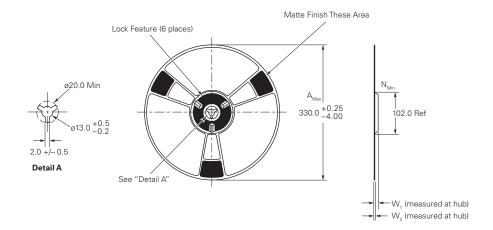


Notes:

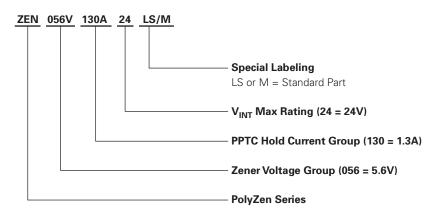
- 1. 10 sprocket hole pitch cumulative tolerance ±0.2
- Camber in compliance with EIA 481
 Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole

Figure PZ26 Reel Dimensions for PolyZen Devices (in Millimeters)

Description Dimension (mm) 330 A_{Max} 102 N_{Min} 8.4 W_2 11.1



Part Numbering System for PolyZen Devices





extstyle ext

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